

X

Explain

Yes No

APPLICATION FOR EXTENSION OF ESCC QUALIFICATION APPROVAL

Component Title: DIODES MICROWAVE, SILICON, PIN,

BASED ON PLANAR TYPES BXY43 AND BXY44
Date: 12.05.2014

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tppi. No.

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1 Components (including series and families) submitted for Qual. App. **ESCC** VARIANTS RANGE OF BASED TEST COMPONENT COMP. NO. COMPONENTS VEHICLE / S SIMILAR ON 5513/030 01 BXY43C 02 **BAS70** BXY43C 05 BXY44K 06 BXY44K 2 3 4 Component Manufacturer Location of manufacturing plant Date of original qualification approval Infineon Technologies AG Oct. 1996 Am Campeon 1-12 Certificate Ref. No. 236 D-85579 Neubiberg Germany 5 6 7 ESCC Specifications used for Deviations for testing level B, Qualification Extension Report ref. maintenance LAT1 and Detail Spec. used: and date: Generic: ESCC 5010 Iss. 1, 2002 No ⊠ Yes □ (supply details) 1410LR10.pdf Details: ESCC 5513/030 Iss. 1, 2002 (in Box 15) Issue 1 April 2014 Deviation from current Spec. No ⊠ Yes □ (supply details) 8 Summary of procurement or equivalent test results during current validity period in support of this application (those to ESCC listed first) Project Name Testing Level LAT Date code Quantity Delivered Various 3 lots since 1030A 13xx (3 lots) 9 10 PID Changes since Original Qual. Current PID Verified by: DLR J. Tetzlaff or last extension of Qual. Name Executive Responsible Ref. No.: A63500-D329-A1-*-76K5 None Issue: 3 Minor* * provide detail Date: 1999-12-15 Major* Rev: Date: 1999-12-10 see remark in box 14 11 Current Manufacturing Facilities surveyed by J. Tetzlaff on 17.09.2010 (Name Executive Responsible) (date) Satisfactory:



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236 F Date: 12.05.2014 12 Failure Analysis, DPA, NCCS available: Yes No X (supply data) Ref. No's and purpes: 13 The undersigned hereby certifies on behalf of the ESCC Executive, that the above information is correct; that the appropriate documentation has been evaluated; that full compliance to all ESCC requirements is evidence except as stated in box 15; that the reports and data are available at the ESCC Executive and therefore applies for ESCC qualification status to be extended to the component(s) listed herein. Date: 12.05.2014 i.A. G. Joormann (Signature of the ESCC Executive Representative) 14 Continuation of Boxes above: As agreed on the MOQ Audit, together with ESA, PID will be updated, when the new ESCC 5010 is available.



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		BASED C	Dat		236 F	
Non compliance t	o ESCC requirements:					15
No.:	Specification		Paragraph		Non compliance	
						16
ESCC Disposition	n:					17
Application Aprova		No 🗆				
Action/Remarks:	ai. Tes	NO D				
. Caroni Comund.						
Date:				SCSB Chairm		